Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **VDD**
2. **GND**
3. **TTL OUT**
4. **IN –**
5. **GND**
6. **IN +**



**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: GND**

**Mask Ref: A**

**APPROVED BY: DK DIE SIZE .032” X .034” DATE: 6/30/17**

**MFG: NATIONAL SEMI THICKNESS .010” P/N: DS90LV012A MDC**

**DG 10.1.2**

#### Rev B, 7/19/02